



Material Content Data Sheet



Sales Product Name		BSS84PW H6327		Issued		24. January 2018			
MA#		MA001683324							
Package		PG-SOT323-3-3		Weight*		5.97 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.002	0.03		289		
	noble metal	gold	7440-57-5	0.007	0.11		1119		
	inorganic material	silicon	7440-21-3	0.076	1.27	1.41	12686	14094	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88		
	non noble metal	titanium	7440-32-6	0.003	0.04		440		
	non noble metal	chromium	7440-47-3	0.008	0.13		1321		
	non noble metal	copper	7440-50-8	2.617	43.84	44.02	438414	440263	
wire	non noble metal	copper	7440-50-8	0.005	0.09	0.09	852	852	
encapsulation	organic material	carbon black	1333-86-4	0.031	0.52		5209		
	plastics	epoxy resin	-	0.668	11.20		111990		
	inorganic material	silicondioxide	60676-86-0	2.410	40.37	52.09	403684	520883	
leadfinish	non noble metal	tin	7440-31-5	0.133	2.22	2.22	22231	22231	
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1677	1677	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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